CLAIMS

[1] A driver module structure comprising:

a flexible circuit board provided with a wiring pattern;

a semiconductor device mounted on the flexible circuit board; and

an electrically conductive heat-radiating member joined to the semiconductor device,

wherein the wiring pattern comprises a ground wiring pattern,

the flexible circuit board has a cavity that exposes a portion of the ground wiring pattern, and

the exposed portion of the ground wiring pattern and the heat-radiating member are connected to establish electrical continuity via a member that is fitted into the cavity.

[2] The driver module structure according to claim 1, wherein the cavity is a recess for exposing a portion of the ground wiring pattern to the heat-radiating member, and the member fitted into the cavity is a projection of the heat-radiating member.

[3] The driver module structure according to claim 2, wherein the exposed portion of the ground wiring pattern and the projection are connected via an electrically conductive bonding material.

[4] The driver module structure according to claim 1, wherein the cavity is a through hole penetrating the ground wiring pattern, a portion of the ground wiring pattern on an opposite side from the heat-radiating member is exposed, and the member fitted into the cavity is a projection of the heat-radiating member.

[5] The driver module structure according to claim 4, wherein the projection is hollow, and an end of the projection is deformed so that the exposed portion of the ground wiring pattern and the projection are connected to establish electrical continuity.

[6] The driver module structure according to claim 4, wherein the exposed portion of the ground wiring pattern and the projection are connected

via an electrically conductive bonding material.

[7] The driver module structure according to claim 1, wherein the cavity is a through hole penetrating the ground wiring pattern, a portion of the ground wiring pattern on an opposite side from the heat-radiating member is exposed, and the member fitted into the cavity is a fastener for fastening the flexible circuit board and the heat-radiating member.

[8] The driver module structure according to claim 7, wherein the exposed portion of the ground wiring pattern and the fastener are connected via an electrically conductive bonding material.